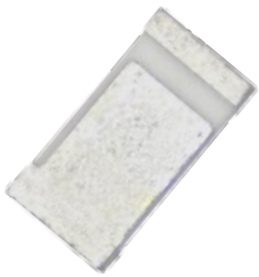
Wi-Fi / Bluetooth

ST0243-00-N02-B

Amphenol

Datasheet

2.4-2.5GHz
Chip antenna



5 X 3 X 0.5 mm

Chip Antenna

Features:

High performing Wi-Fi & Bluetooth antenna with SMT mounting on PCB.

Applications:

- CPE - Router, Set-top boxes & Gateway
- IoT devices
- Wi-Fi & Bluetooth Mesh
- Smart Metering
- Robotics

RoHS

Electrical Specifications

Antenna Characteristics

Antenna Type	Radiation Pattern	Polarization	Max. Input Power	Impedance
Chip Antenna	Omni	Linear	1W	50Ω

Frequency (GHz)	**2.4~2.5**
Return Loss (dB)	< -10
Peak Gain (dBi)	2.3
Average Gain (dB)	-1.6
Efficiency (%)	69

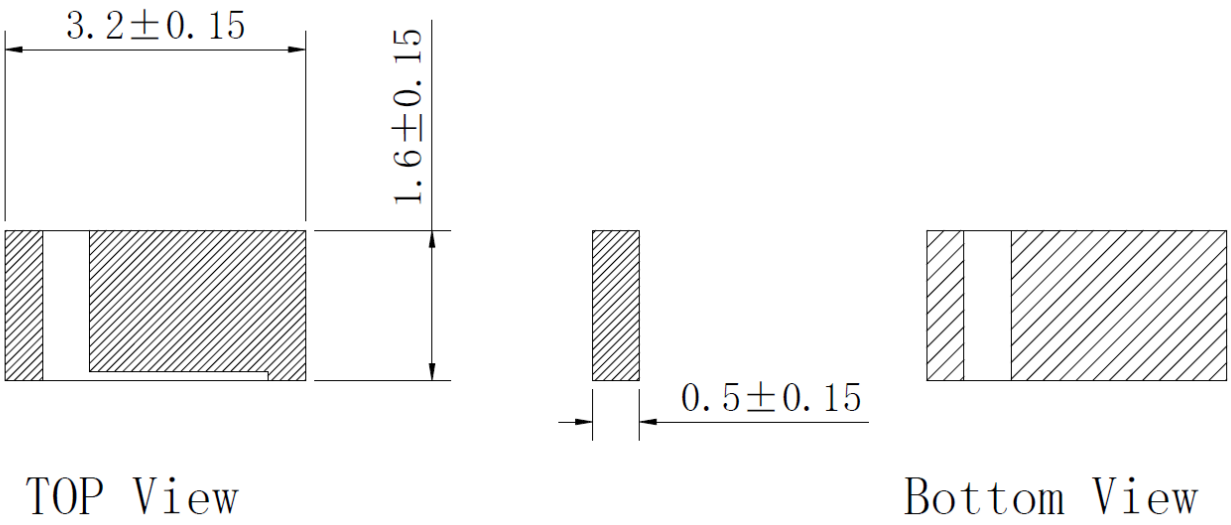
Mechanical Specifications

Environmental	
Temperature Range (˚C)	-25 to 70
Humidity	Non-condensing 65°C 95% RH
RoHS Compliant	

Part Number	Dimension (mm)	Weight (g)	Material
ST0243-00-N02-B	3.2 X 1.6 X 0.5	0.01	Ceramic

Mechanical Drawing

Unit : mm



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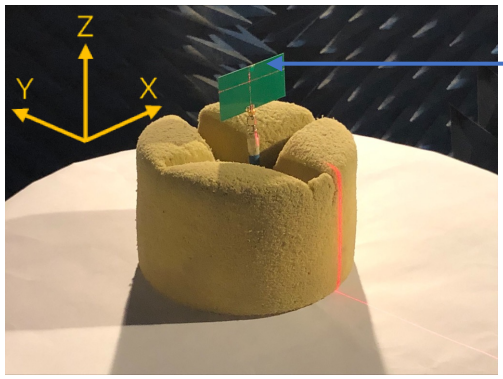
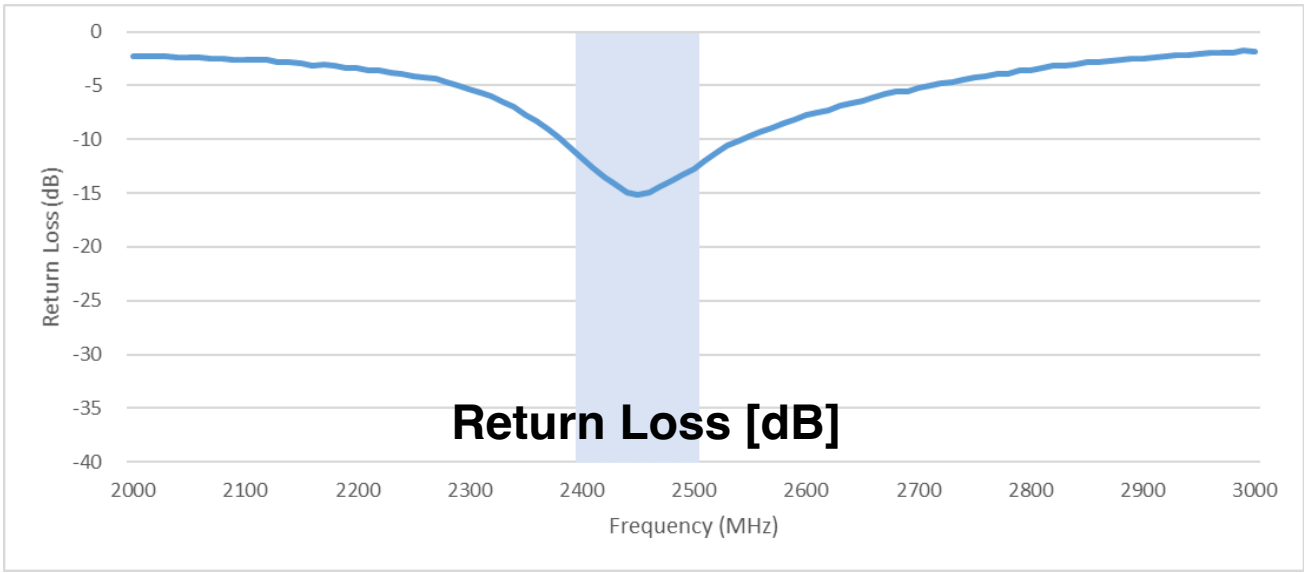
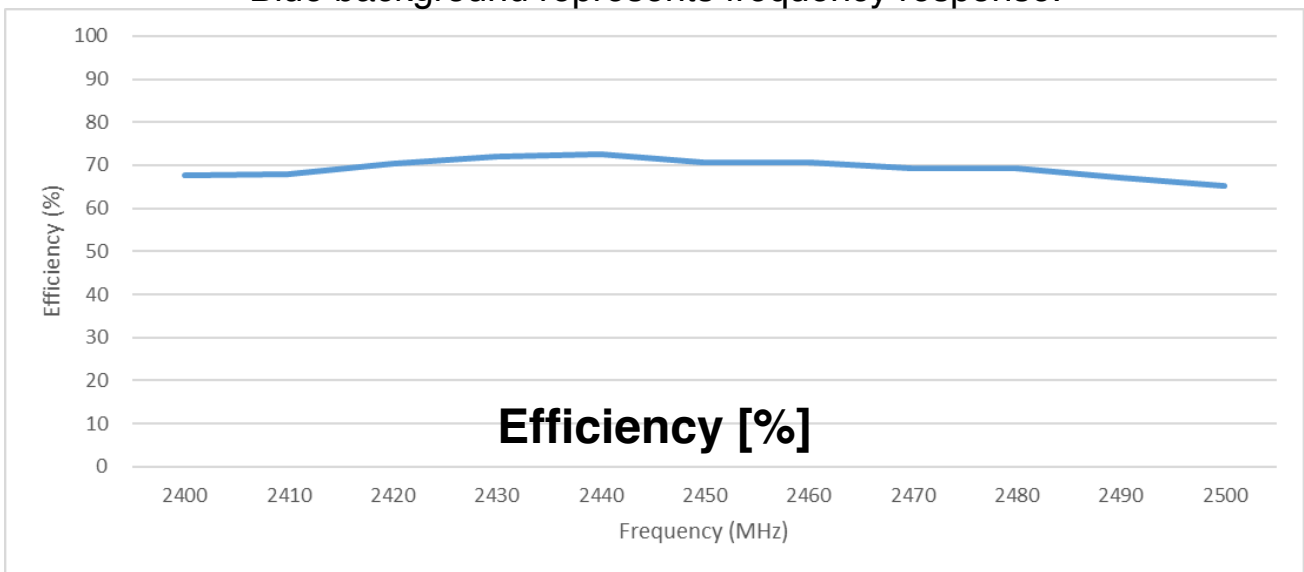
Antenna Testing Includes Evaluation Board



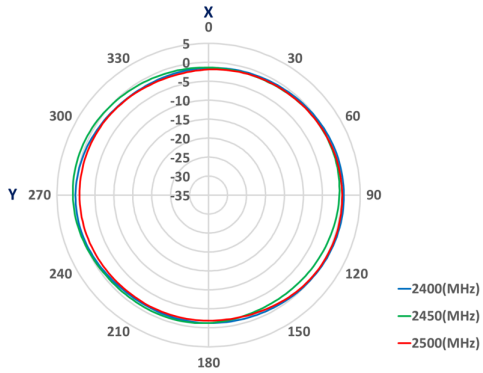
Test setup, measurement performed in 3D anechoic chamber.



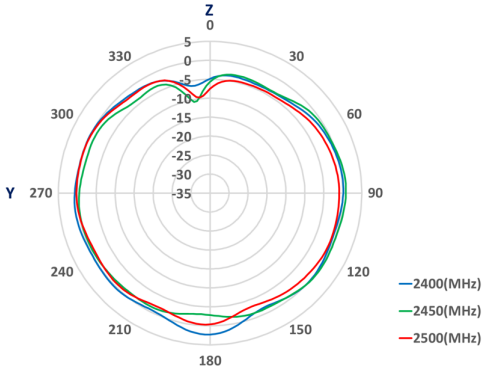
Blue background represents frequency response.



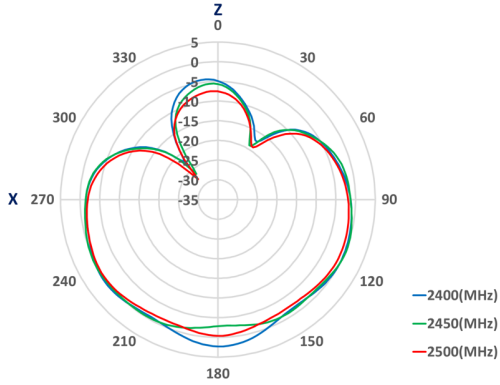
XY - Plane



YZ - Plane

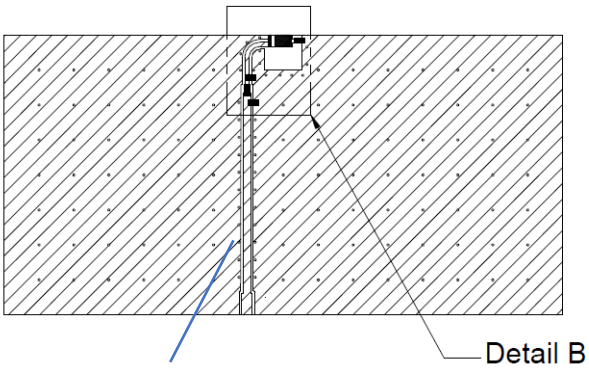


XZ - Plane

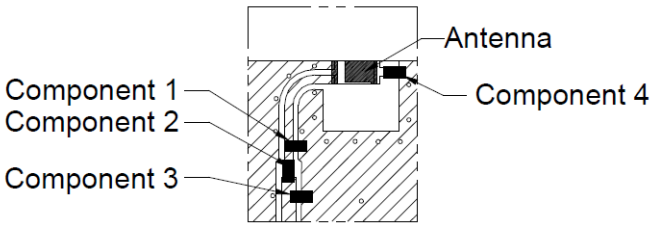


Matching Circuit Design

Unit : mm



50Ω Transmission



Detail B

Cu Top Layer

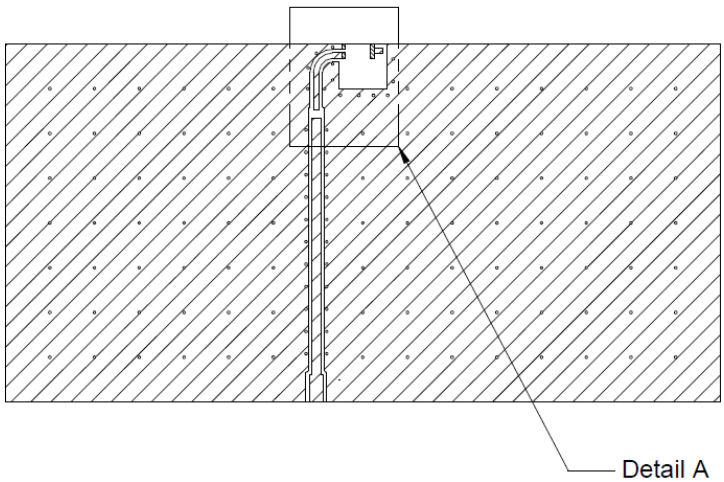
* To make the antenna have this resonance, must be matched with matching circuit.
* The matching component may be slightly different than that show depending ondistance to ground plane, dielectric constant of PCB, and PCB material thickness.

Circuit Matching Components

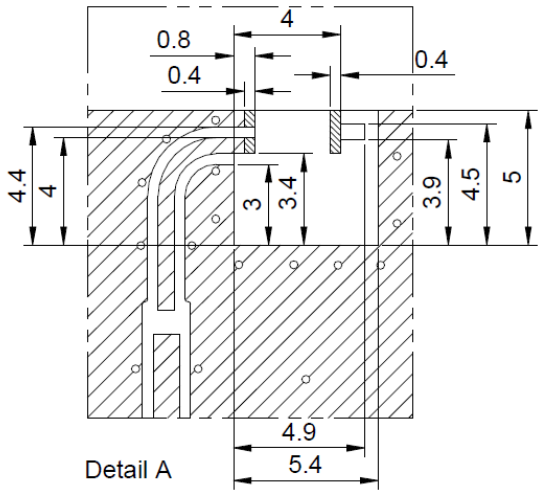
Circuit Symbol	Size	Description
Component 1	0402	None
Component 2	0402	0Ohm Resistance
Component 3	0402	20pF Capacitor
Component 4	0402	8pF Capacitor

Clearance Area Design

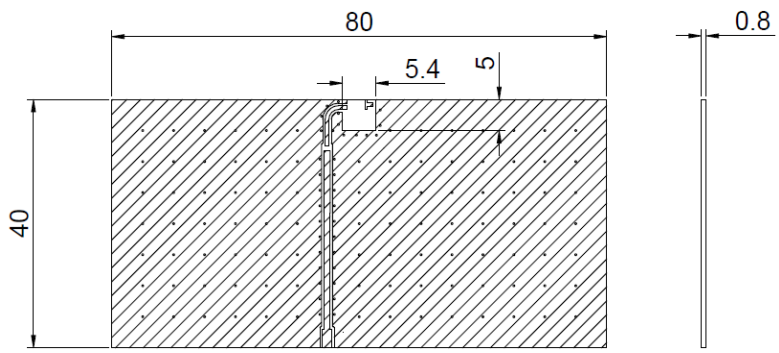
Unit : mm



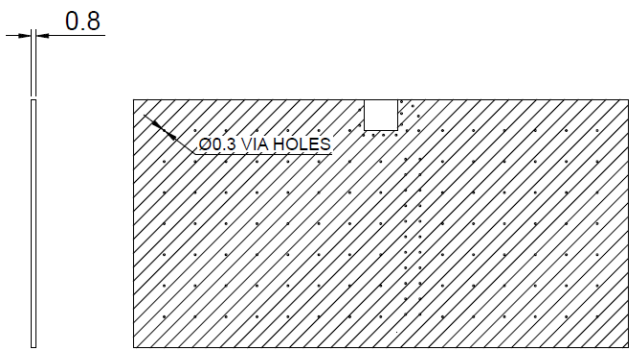
Cu Top Layer



Evaluation Board



Cu Top Layer



Cu Bottom Layer

Base Material : FR-4

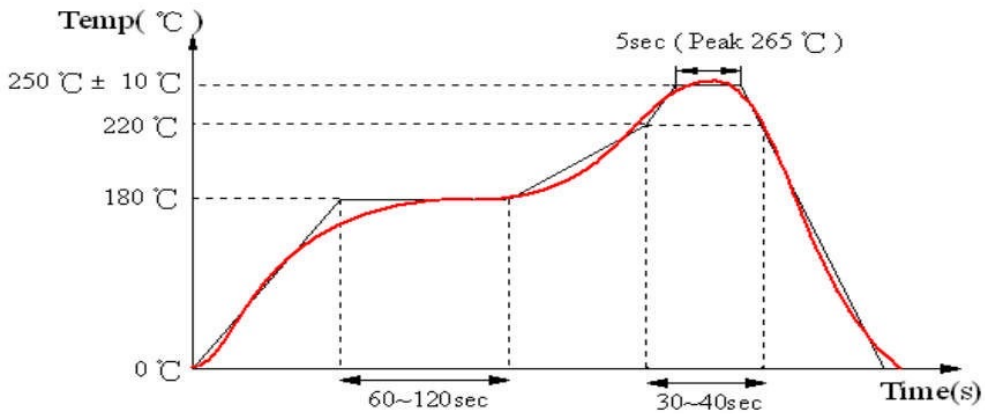
Recommended Reflow Temperature Profile

Flux :

- Use rosin flux, prohibit the use of strong acid flux with halide content exceeding 0.2wt%.
- Use pure tin solder.

Reflow Soldering Conditions :

- During preheating, the maximum temperature difference between the surface of the product and the solder is not allowed to exceed 150˚C.
- When cooling down after soldering, the temperature difference between the surface of the product and the solvent is not allowed to exceed 100˚C.
- Insufficient preheating may cause cracks on the product surface, resulting in a decline in product quality.



The graphic shows temperature profile component assembly process in reflow ovens.

Soldering With Iron

Soldering condition

Item	The conditions
Pre-heating	150˚C, 1 Minute
Tip temperature	350˚C Max.
Soldering iron output	80W Max.
End of soldering	Φ3mm Max.
Soldering time	3 Seconds Max.

Revisions				
Rev.	Description	Date	ECN	Approval
A	Initial Release	2022-12-26	ST0243-00-N02-B-RA00	ATC